External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.41169	100.0	4.4
			Subtotal	0.41169	100	4.4
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03752	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01126	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03752	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.43385	99.77	400.0777
			Subtotal	37.52015	100	401
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.84292	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.92276	10.0	63.3
	Filler	Silica fused	60676-86-0	50.34343	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11846	0.2	1.266
			Subtotal	59.22757	100	633
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.33916	100.0	25
			Subtotal	2.33916	100	25
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01395	100.0	0.1491
	Pure metal	Aluminium (Al)	7429-90-5	0.23017	100.0	2.46
			Subtotal	0.24412	200	2.6091
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00515	2.0	0.055
	Lead alloy	Silver (Ag)	7440-22-4	0.00643	2.5	0.06875
	Lead alloy	Lead (Pb)	7439-92-1	0.24573	95.5	2.62625
			Subtotal	0.25731	100	2.75
			Total	100	100	1068.7591

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